

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3242821

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TOHRU MATSUMOTO	12/15/2014
MASARU OGASAWARA	12/15/2014
MITSUAKI TODA	12/08/2014
RECEIVING PARTY DATA	
Name:	MEIKO ELECTRONICS CO., LTD.
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City:	AYASE-SHI, KANAGAWA
State/Country:	JAPAN
Postal Code:	252-1104
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14423990
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SIGNATURE:	/David C. Read/
DATE SIGNED:	02/26/2015
Total Attachments: 2	
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source=Complete_Assignment#page2.tif	

ASSIGNMENT

Serial No: 14/423,990

Filed: February 25, 2015

Title: MANUFACTURING METHOD OF DEVICE EMBEDDED SUBSTRATE AND
DEVICE EMBEDDED SUBSTRATE MANUFACTURED BY THIS METHOD

For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the undersigned hereby assign to MEIKO ELECTRONICS CO., LTD., 5-14-15, Ogami, Ayase-shi, Kanagawa 252-1104, Japan, (hereinafter "Assignee"), its successors and assigns, the entire right, title and interest in the invention or improvements of the undersigned disclosed in an application for letters patent of the United States, executed by the undersigned on,

December 15, 2014 and December 8, 2014

and in said application and any and all other applications, both in the United States and in other countries, which the undersigned may file or be named as an inventor, either solely or jointly with others, on said invention or improvements, and in any and all letters patent of the United States and other countries, which may be obtained on any of said applications, and in any reissue or extension thereof.

The undersigned hereby authorize and request the Commissioner for Patents to issue said letters patent to said Assignee.

The undersigned hereby authorize and request that the attorneys of record in said application insert in this assignment the execution date and/or filing date and serial number of said application when officially known.

The undersigned warrant themselves to be the owners of the interest herein assigned and to have the right to make this assignment and further warrant that there are no outstanding prior assignments, licenses, or other rights in the interest herein assigned except in favor of Assignee.

For said consideration the undersigned hereby agree, upon the request and at the expense of said Assignee, its successors and assigns, to execute any and all applications on said invention or improvements, and any necessary oath or affidavit relating thereto, and any application for the reissue or extension of any letters patent that may be granted upon any and all of said applications, and any and all applications and other documents for letters patent in other countries on said invention or improvements, that said Assignee, its successors or assigns, may deem necessary or expedient, and for said consideration the undersigned further

agree upon the request of said Assignee, its successors or assigns, in the event of any application or letters patent assigned herein becoming involved in Interference or Opposition, to cooperate to the best of the ability of the undersigned with said Assignee, its successors or assigns, in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof, the undersigned hereby agreeing to perform, upon request, any and all affirmative acts to obtain said letters patent, both in the United States and in other countries, and vest all rights therein hereby conveyed in said Assignee, its successors and assigns, whereby said letters patent will be held and enjoyed by said Assignee, its successors and assigns, to the full end of the term for which said letters patent may be granted as fully and entirely as the same would have been held and enjoyed by the undersigned if this assignment and sale had not been made.

Date: 2014 / 12 / 15

Signature: Tohru MATSUMOTO
Tohru MATSUMOTO

Date: 2014 / 12 / 15

Signature: Masaru OGASAWARA
Masaru OGASAWARA

Date: 2014 / 12 / 18

Signature: Mitsuaki TODA
Mitsuaki TODA